



UMC

With the rise of AIoT, 5G, edge-computing and sophisticated automotive ICs, UMC customers today enjoy unprecedented opportunities to develop a wide variety of chips needed to power the global economy. UMC is sharply focused on delivering specialty technology solutions and platforms that enable customers to take advantage of these rapidly growing product applications. Our open collaboration and customized approach help us meet our goal of delivering differentiated specialty technologies, comprehensive foundry resources, and world-class manufacturing to our global customers.



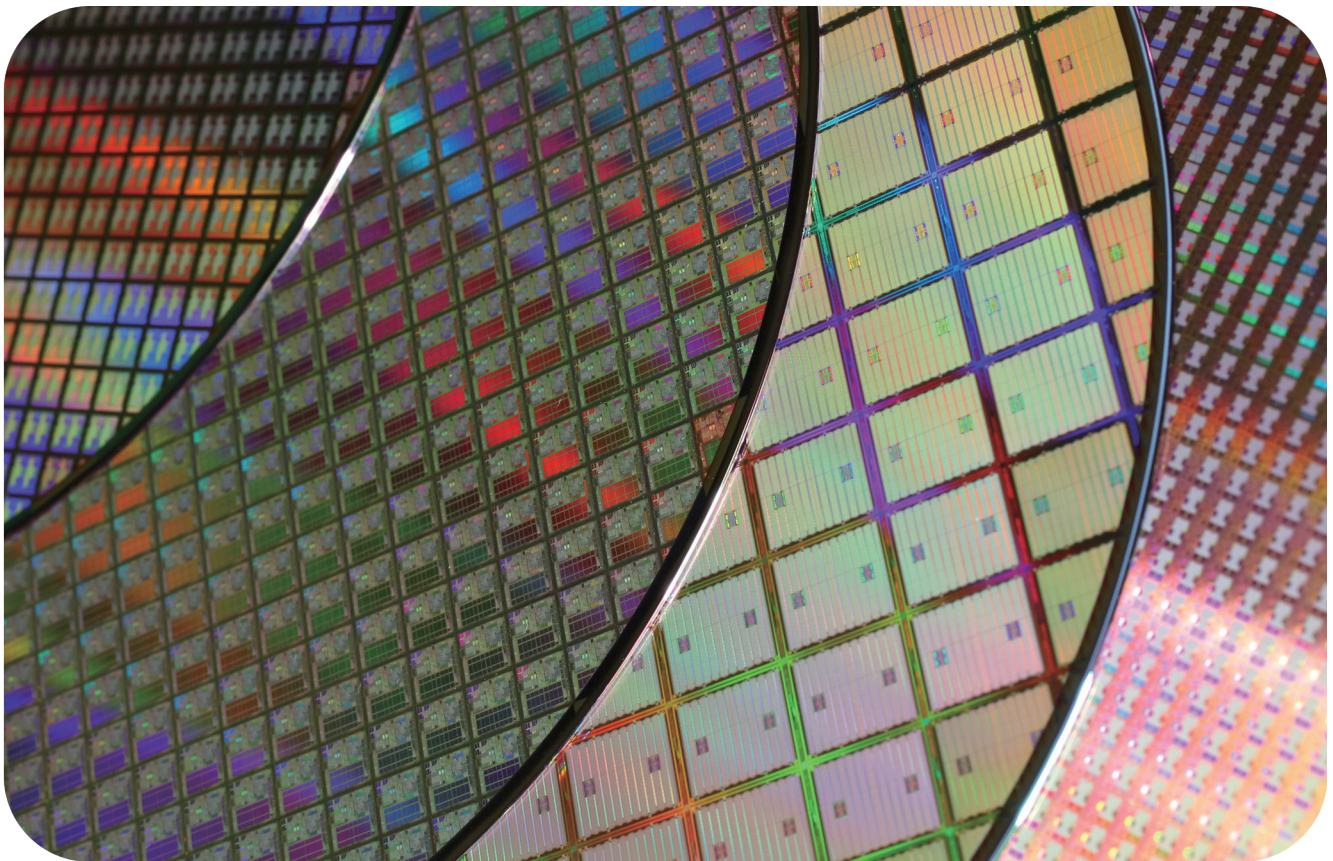
Shan-Chieh Chien

Shan-Chieh Chien, President



Jason Wang

Jason Wang, President



UMC Profile

Full Company Name	United Microelectronics Corporation
Founded	1980
Headquarters	No. 3, Li-Hsin 2nd Rd., Hsinchu Science Park, Hsinchu, Taiwan
Global Locations	Fabs: Taiwan, Singapore, China, Japan Offices: China, Europe, Japan, Korea, Singapore, Taiwan, U.S.A.
Number of Employees	Approximately 20,000 Worldwide
Core Competencies	Pure-play foundry with internal R&D capability, world-class 200/300mm manufacturing, solid engineering base, and a comprehensive range of process technologies.
Technologies	CMOS Logic from 5µm to 14nm FinFET, HV, RF, Mixed Signal, MEMS, Automotive, CIS, eNVM
Chairman	Stan Hung
Co-presidents	Shan-Chieh Chien, Jason Wang
Stock Listing	NYSE: UMC, TWSE: 2303

UMC (NYSE: UMC, TWSE: 2303) is a leading global semiconductor foundry company. The company provides high quality IC fabrication services, focusing on logic and various specialty technologies to serve all major sectors of the electronics industry. UMC's comprehensive IC processing technologies and manufacturing solutions include Logic/Mixed-Signal, embedded High-Voltage, embedded Non-Volatile-Memory, RFSOI and BCD etc. Most of UMC's 12-inch & 8-inch fabs with its core R&D are located in Taiwan,

with additional ones throughout Asia. UMC has total 12 fabs in production with combined capacity over 850,000 wafers per month (8-inch equivalent), and all of them are certified with IATF 16949 automotive quality standard. UMC is headquartered in Hsinchu, Taiwan, plus local offices in United States, Europe, China, Japan, Korea & Singapore, with worldwide total 20,000 employees. For more information, please visit: <http://www.umc.com>.

Comprehensive Foundry Solutions

Comprehensive Platform

UMC collaborates closely with customers as well as our partners throughout the supply chain to work synergistically towards first-pass silicon success.

UMC's foundry solutions start from a logic-based platform, where designers choose the process technologies and transistor options that best fit their application. From there, technologies such as RFCMOS and embedded memory can be used to fine-tune the process. Furthermore, we provide basic IP building blocks as well as more complex IP that are optimized for performance and cost, developed both internally and from third-party partners.

With a wide range of technologies, broad IP portfolio, system knowledge, and advanced 300mm manufacturing, UMC offers comprehensive solutions that help customers deliver successful results in a timely fashion.

World-Class Manufacturing

UMC is a global manufacturing leader with 12 fabs located throughout Asia. Fab 12A was Taiwan's first 300mm fab, and has been in volume production since 2002. This advanced facility consists of Phases 1-6 and is currently manufacturing customer products using 28nm High-K/Metal gate and 14nm FinFET technologies. UMC's second 300mm fab, Fab 12i,

is located in Singapore. This facility is our Specialty Technology Center that provides highly specialized processes on 300mm manufacturing to serve a diverse range of product applications.

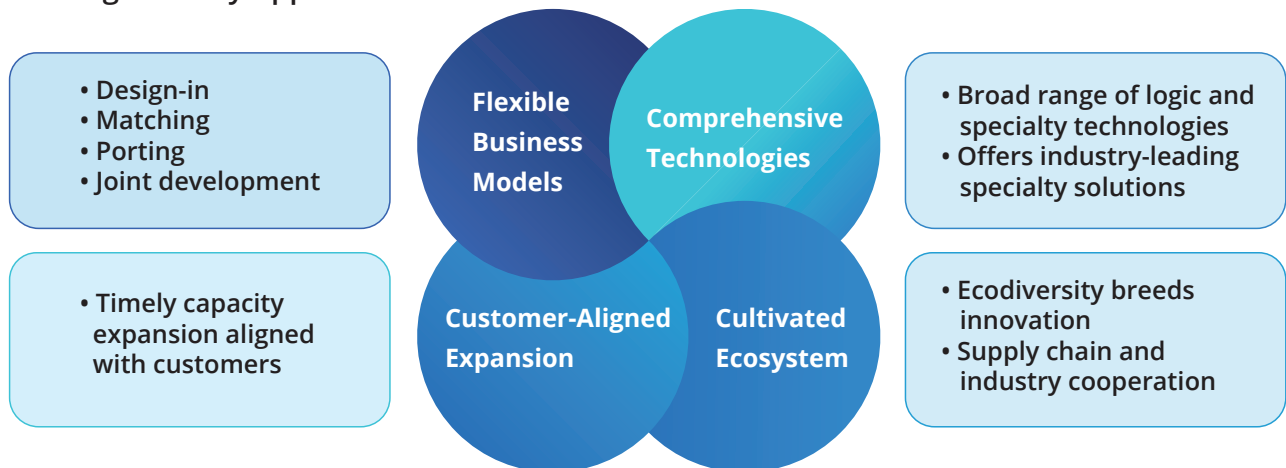
United Semi 300mm fab (Fab 12X), located in Xiamen, China, began volume production in 2016. United Semi serves the fast growing China market for IoT products and provides further geographic manufacturing diversity for our foundry customers.

Japan-based USJC (Fab 12M), fully acquired in October of 2019, is UMC's fourth 300mm fab. USJC offers foundry volume production for specialty process technologies ranging from 90nm to 40nm.

In addition, UMC's expertise accumulated over four decades ensures industry-leading manufacturing quality. Comprehensive process control systems with advanced methodologies and a strong engineering team support fast product ramp.

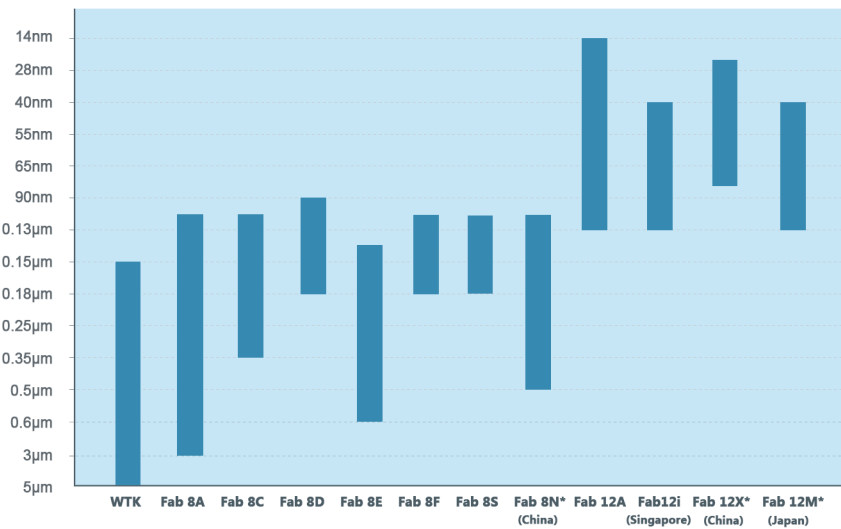
UMC's advanced automation, mature defect density, fast cycle times and ample capacity enable UMC to provide the most competitive manufacturing advantages for our foundry customers.

A Winning Foundry Approach



Broad Technologies in Multiple Fabs

A broad range of technologies span across UMC's 12 fabs. This provides customers with multiple manufacturing options using the same process technologies to diversify risk and ensure stable IC supply.



Verified Package Solutions

Solutions	Capability
Bump / Flip Chip	6" / 8" / 12" wafer
	14 / 22 / 28nm & above
	Leadfree (Sn-Ag) / Cu pillar bump
	Au bump / COF / COG / COP
	WLP (Fan-in & Fan-out)
Wire Bond / BOAC	14 / 22 / 28nm & above
	Au / Cu / Ag wire
MCP / SiP	Stacked die / Side by side / POP
Advanced Packaging	2.5D TSI / 3DIC TSV / Hybrid bond

Package/Testing Partners

UMC's major test and package subcontractors are located in Taiwan and throughout Asia. The close proximity of UMC's test and package partners to UMC creates synergies that enable faster service and greater flexibility.

Bump / WLP	2.5D / 3DIC	CP	Package	FT
Amkor ASE ChipBond ChipMOS JCET / jcap TFME UTAC SPIL Winstek	Amkor ASE SPIL	Amkor Ardentec ASE Chipbond ChipMOS Greatek JCET / jcap KYEC Sigurd SPIL TFME UTAC Winstek YTEC	Amkor ASE Chipbond ChipMOS Greatek JCET / jcap SPIL TFME UTAC Winstek	Amkor ASE SPIL



Sustainability at UMC

Our Commitment

UMC endeavors to run our business sustainably in order to realize stable, long-term growth. We also aim to establish strong relationships with our customers, suppliers, and other stakeholders. Driven by our ESG vision, UMC actively take steps to protect the environment, improve employee welfare, and give back to the communities in which we operate. Since 2008, UMC has been selected for inclusion in the Dow Jones Sustainability Indices (DJSI), one of the most important benchmarks for sustainable investing.

Sustainability Strategy Blueprint

UMC's ESG Steering Committee set the 2030 Sustainability Strategy Blueprint, which defines each ESG dimension and corresponding goals. To minimize our environmental footprint, UMC is committed to achieving net zero emissions by 2050, and is proactively reducing resource consumption and greenhouse gas emissions under the "Green 2025" initiative. We aim to provide a safe and friendly workplace for our employees, while sharing resources with partners to create social value. Leveraging our core capabilities, UMC also strives to strengthen governance and be trusted partner of all our stakeholders.

Net Zero Emissions by 2050

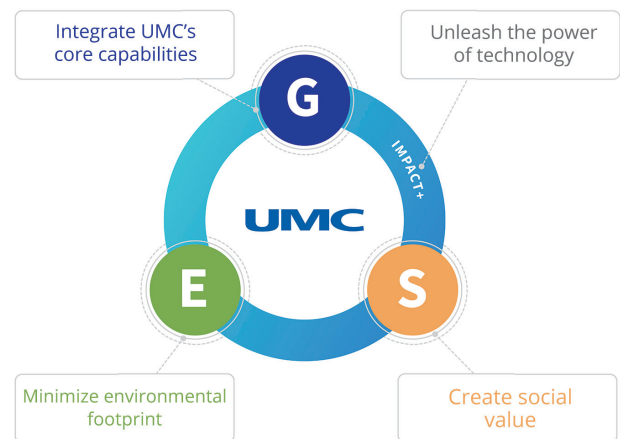
In June 2021, UMC announced our pledge to achieve net zero greenhouse gas emissions by 2050, the first in the semiconductor foundry industry to make such a commitment. As a member of RE100, we also aim to use renewable energy sources for 100% of our electricity consumption by 2050. To honor our commitment, UMC will systematically reduce emissions from our operations as well as work with customers and suppliers to realize a greener value chain.

Vision

To strive for a better and more sustainable future that is centered on people, in harmony with the environment, and enables communities to thrive.

Mission

To pursue sustainable growth by embracing innovation and corporate responsibility, and to enable customers to meet the challenges of sustainable development.



Global Operations

UMC has offices in North America, Europe and throughout Asia to serve its global customers. The company's manufacturing base consists of 12 wafer fabs, including advanced 300mm facilities in Taiwan, Singapore, Japan and China.



Worldwide Contacts

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